Power MOSFET

40 V, 2.8 m Ω , 110 A, Single N-Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5C450NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	40	V
Gate-to-Source Voltage	Э		V _{GS}	±20	V
Continuous Drain		T _C = 25°C	I _D	110	Α
Current R _{θJC} (Notes 1, 3)	Steady	T _C = 100°C		81	
Power Dissipation	State	T _C = 25°C	P _D	68	W
R _{θJC} (Note 1)		T _C = 100°C		34	
Continuous Drain		T _A = 25°C	I _D	27	Α
Current R _{θJA} (Notes 1, 2, 3)	Steady	T _A = 100°C		19	
Power Dissipation	State	T _A = 25°C	P_{D}	3.7	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C		1.6	
Pulsed Drain Current	T _A = 25	$T_A = 25^{\circ}C, t_p = 10 \mu s$		740	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	–55 to + 175	°C
Source Current (Body Diode)			I _S	76	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 7 A)			E _{AS}	215	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	2.2	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	41	

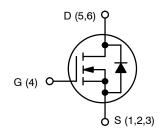
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



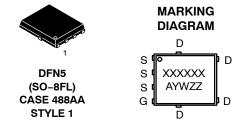
ON Semiconductor®

www.onsemi.com

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
40 V	2.8 mΩ @ 10 V	110 A	
	4.4 mΩ @ 4.5 V	HOA	



N-CHANNEL MOSFET



XXXXXX = 5C450L

(NVMFS5C450NL) or

450LWF

(NVMFS5C450NLWF)

A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS	•				•	•	•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		40			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /				1.6		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C			10		
		$V_{DS} = 40 \text{ V}$	T _J = 125°C			250	μΑ	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _G	iS = 20 V			100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D} = 60 \mu A$		1.2		2.0	V	
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.3		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 4.5 V	I _D = 40 A		3.5	4.4	mΩ	
		V _{GS} = 10 V	I _D = 40 A		2.3	2.8	1	
Forward Transconductance	9 _{FS}	V _{DS} =15 V, I _D = 40 A			120		S	
CHARGES, CAPACITANCES & GATE F	RESISTANCE					•	•	
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 20 V			2100			
Output Capacitance	C _{OSS}				1000		pF	
Reverse Transfer Capacitance	C _{RSS}			42				
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 20 V; I _D = 40 A			16		nC	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 20 V; I _D = 40 A			35		nC	
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _{DS} = 20 V; I _D = 40 A			4			
Gate-to-Source Charge	Q _{GS}				7		nC	
Gate-to-Drain Charge	Q_{GD}				5		1	
Plateau Voltage	V_{GP}				3.2		V	
SWITCHING CHARACTERISTICS (Note	9 5)						•	
Turn-On Delay Time	t _{d(ON)}				11			
Rise Time	t _r	V _{GS} = 4.5 V. V	ne = 20 V.		110		1	
Turn-Off Delay Time	t _{d(OFF)}	V_{GS} = 4.5 V, V_{DS} = 20 V, I_{D} = 40 A, R_{G} = 1 Ω			21		ns	
Fall Time	t _f				5			
DRAIN-SOURCE DIODE CHARACTER	ISTICS			ı		ı		
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 \text{ V},$ $T_{J} = 25^{\circ}\text{C}$ $T_{J} = 125^{\circ}\text{C}$	T _J = 25°C		0.84	1.2		
				0.72		V		
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 100 \text{ A}/\mu\text{s,}$ $I_{S} = 40 \text{ A}$			41			
Charge Time	t _a				19		ns	
Discharge Time	t _b				22		1	
Reverse Recovery Charge	Q _{RR}				31		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.

5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

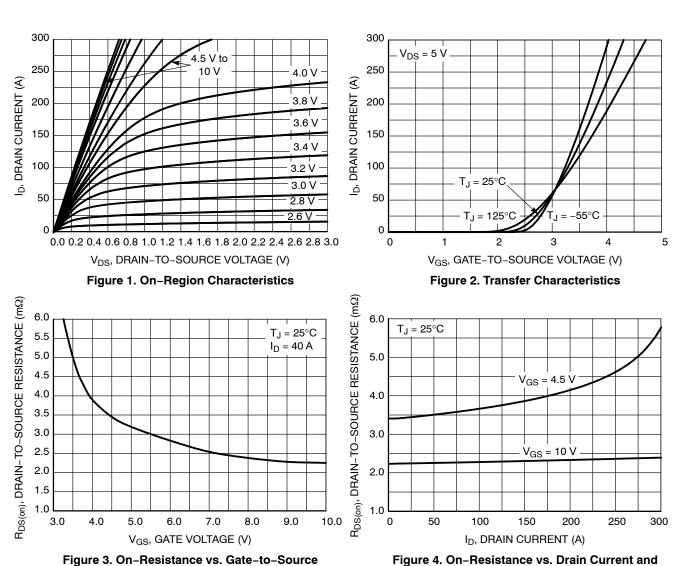


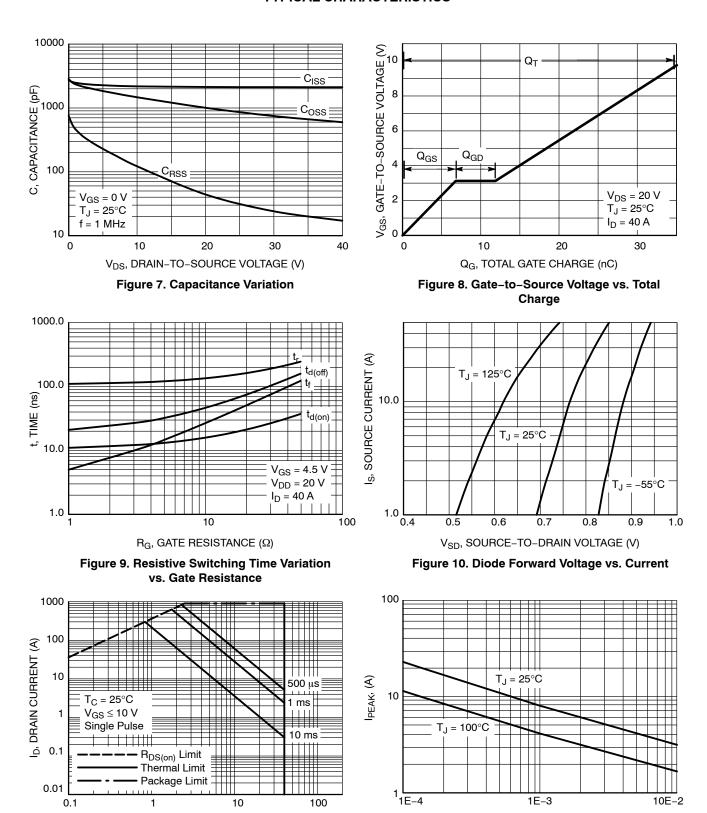
Figure 3. On-Resistance vs. Gate-to-Source Voltage

Gate Voltage 1.9 100000 $V_{GS} = 10 \text{ V}$ R_{DS(on)}, NORMALIZED DRAIN-TO-SOURCE RESISTANCE 0 T E T L 6 T E 2 Y I_D = 40 A $T_{.1} = 150^{\circ}C$ 10000 IDSS, LEAKAGE (nA) $T_J = 125^{\circ}C$ 1000 $T_J = 85^{\circ}C$ 100 0.7 10 -25 0 -50 25 50 75 100 125 5 15 25 35 150 175 T_J, JUNCTION TEMPERATURE (°C) V_{DS}, DRAIN-TO-SOURCE VOLTAGE (V)

Figure 5. On-Resistance Variation with **Temperature**

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS



 $V_{DS}\left(V\right)$ Figure 11. Safe Operating Area

TYPICAL CHARACTERISTICS

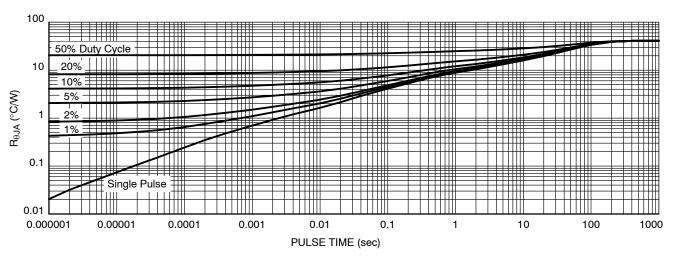


Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]	
NVMFS5C450NLT1G	5C450L	DFN5 (Pb-Free)	1500 / Tape & Reel	
NVMFS5C450NLWFT1G	450LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel	
NVMFS5C450NLT3G	5C450L	DFN5 (Pb-Free)	5000 / Tape & Reel	
NVMFS5C450NLWFT3G	450LWF	DFN5 (Pb-Free, Wettable Flanks)	5000 / Tape & Reel	
NVMFS5C450NLAFT1G	5C450L	DFN5 (Pb-Free)	1500 / Tape & Reel	
NVMFS5C450NLWFAFT1G	450LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



0.10

0.10

SIDE VIEW

DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE N

DATE 25 JUN 2018

NOTES:

BURRS

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е	1.27 BSC			
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
M	3.00	3.40	3.80	
A	0 0		12 °	

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

= Assembly Location Α

Υ = Year W = Work Week ZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.





DETAIL A

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON14036D	Electronic versions are uncontrolled except when accessed directly from the Document Repository Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	DFN5 5x6, 1.27P (SO-8FL)		PAGE 1 OF 1	

ON Semiconductor and unare trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ÓN Semiconductor does not convey any license under its patent rights nor the rights of others

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative